



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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DRC3124T0L

Silicon NPN epitaxial planar type

For digital circuits

Complementary to DRA3124T

DRC9124T in SSSMini3 type package

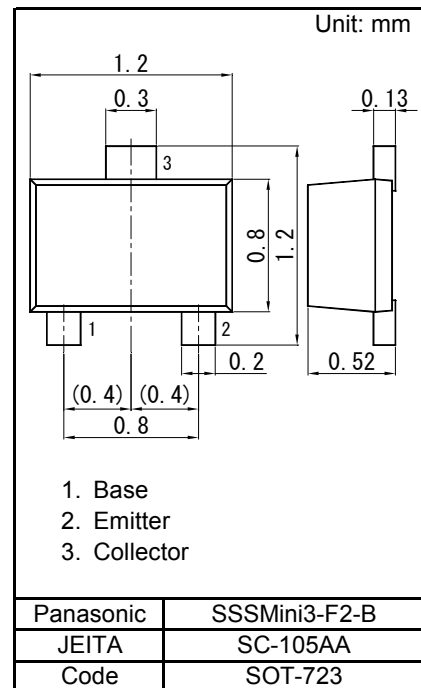
■ Features

- High forward current transfer ratio hFE with excellent linearity
- Low collector-emitter saturation voltage Vce(sat)
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: NH

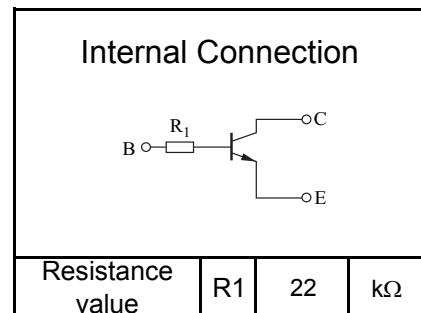
■ Packaging

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|--------|-------------|------|
| Collector-base voltage (Emitter open) | VCBO | 50 | V |
| Collector-emitter voltage (Base open) | VCEO | 50 | V |
| Collector current | IC | 100 | mA |
| Total power dissipation | PT | 100 | mW |
| Junction temperature | Tj | 150 | °C |
| Operating ambient temperature | Topr | -40 to +85 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

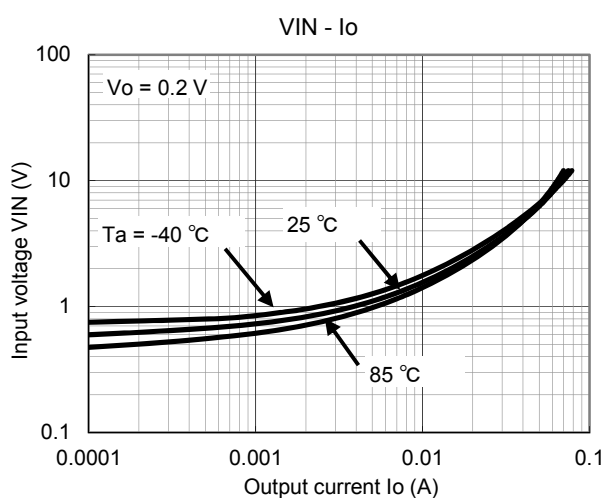
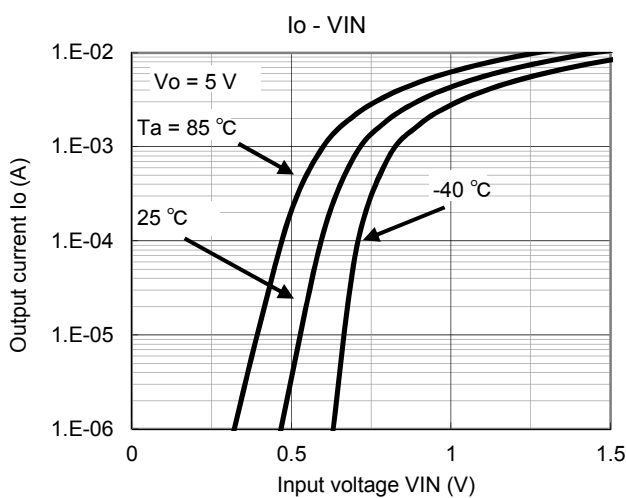
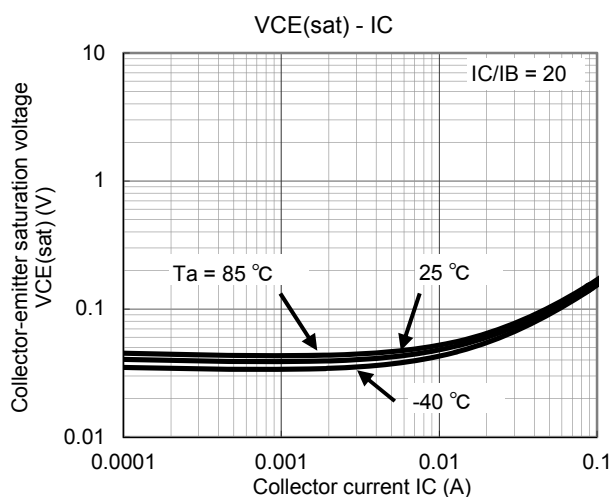
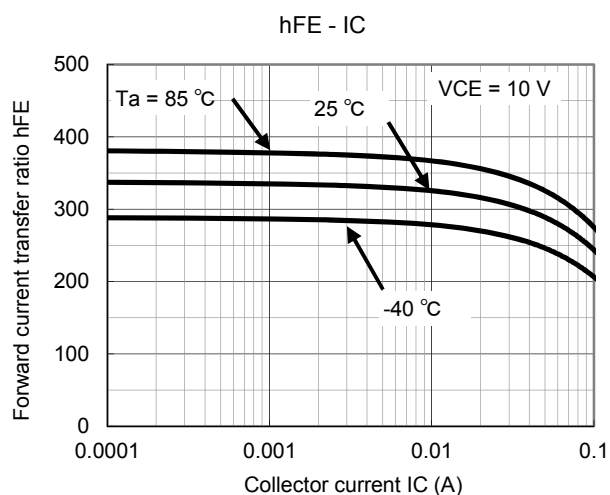
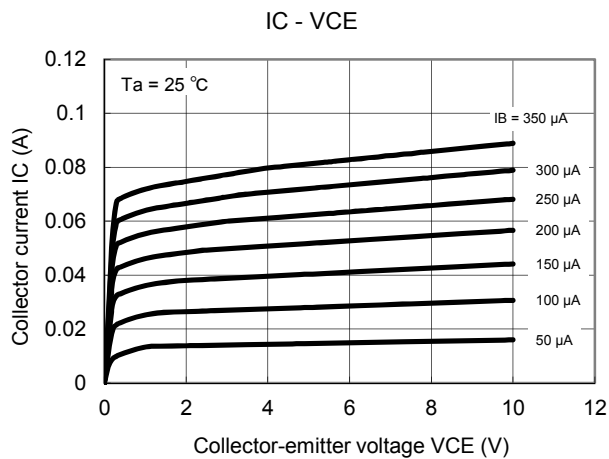
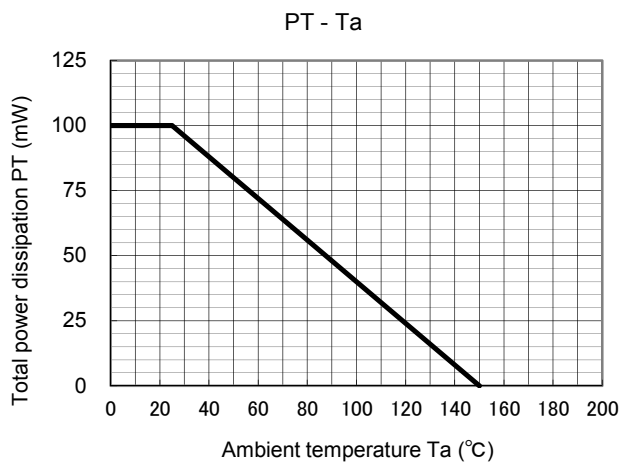


■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|----------|-------------------------|------|-----|------|------|
| Collector-base voltage (Emitter open) | VCBO | IC = 10 μA, IE = 0 | 50 | | | V |
| Collector-emitter voltage (Base open) | VCEO | IC = 2 mA, IB = 0 | 50 | | | V |
| Collector-base cutoff current (Emitter open) | ICBO | VCB = 50 V, IE = 0 | | | 0.1 | μA |
| Collector-emitter cutoff current (Base open) | ICEO | VCE = 50 V, IB = 0 | | | 0.5 | μA |
| Emitter-base cutoff current (Collector open) | IEBO | VEB = 6 V, IC = 0 | | | 0.01 | mA |
| Forward current transfer ratio | hFE | VCE = 10 V, IC = 5 mA | 160 | | 460 | - |
| Collector-emitter saturation voltage | VCE(sat) | IC = 10 mA, IB = 0.5 mA | | | 0.25 | V |
| Input voltage | Vi(on) | VCE = 0.2 V, IC = 5 mA | 1.8 | | | V |
| | Vi(off) | VCE = 5 V, IC = 100 μA | | | 0.4 | V |
| Between emitter base resistance | R1 | | -30% | 22 | +30% | kΩ |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

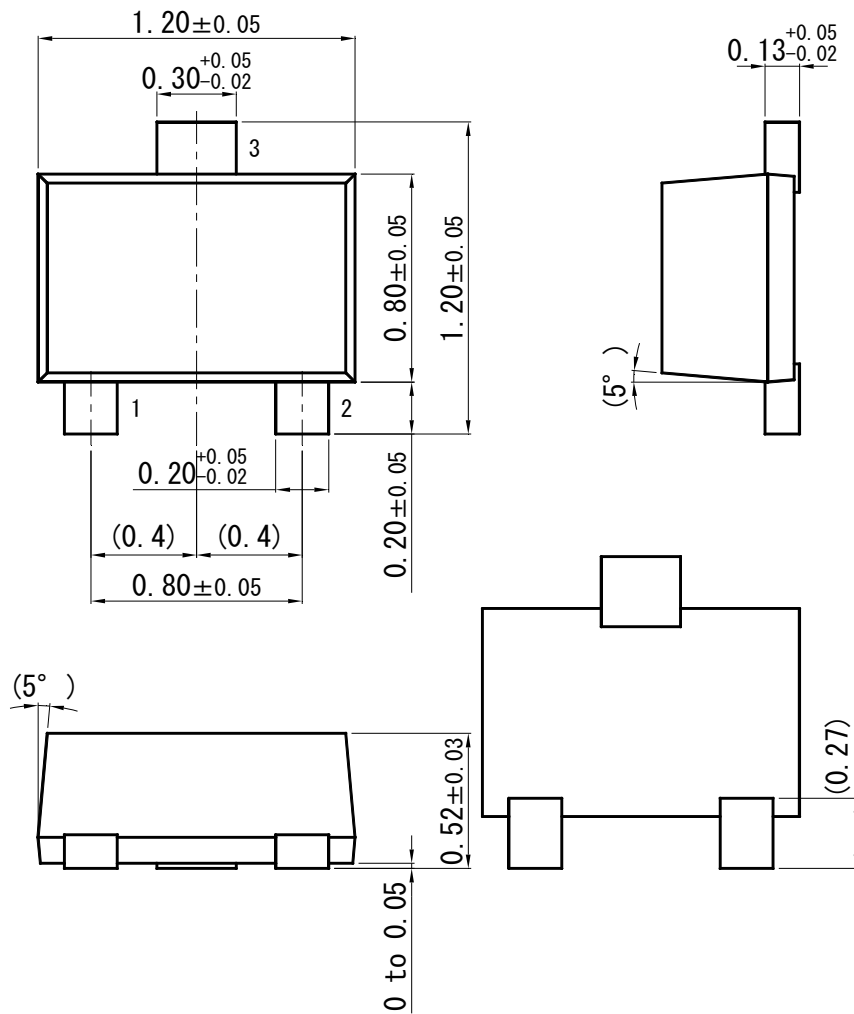
Technical Data (reference)



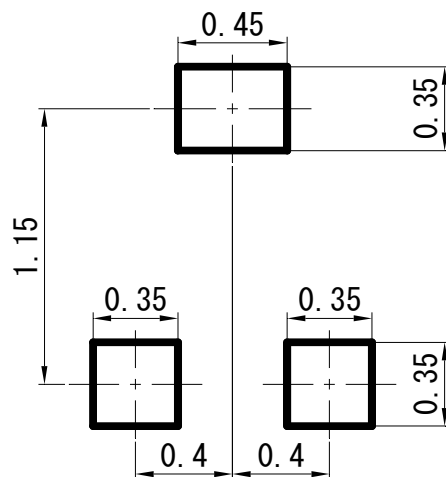


SSSMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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